

# NA-1429

BLS6G3135-120 at 3100-3500 MHz

Rev. 2 — 28 April 2015

Application Measurement  
Report

## Document information

Info	Content
Keywords	NA-1429
Abstract	Measurement results of a demo board for 3100-3500 MHz with 1x BLS6G3135-120.



**Revision history**

Rev	Date	Description
1	20111213	
2	20150424	Update for web publication

**Contact information**

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## 1. Introduction

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### 1.1 General information

This report gives the test results for a 3100-3500MHz demo amplifier (Board NA-1429), using the NXP LDMOS transistor **BLS6G3135-120**. The following test has been performed:

- Pulsed CW @  $V_{DS}=32V$ ,  $I_{DQ}=100mA$ ,  $t_p=300\mu s$ ,  $\delta=10\%$

All testing has been performed at  $V_{DS}=32V$ ,  $I_{DQ}=100mA$  and  $T_H=25^\circ C$ . Data is presented in graphical format.

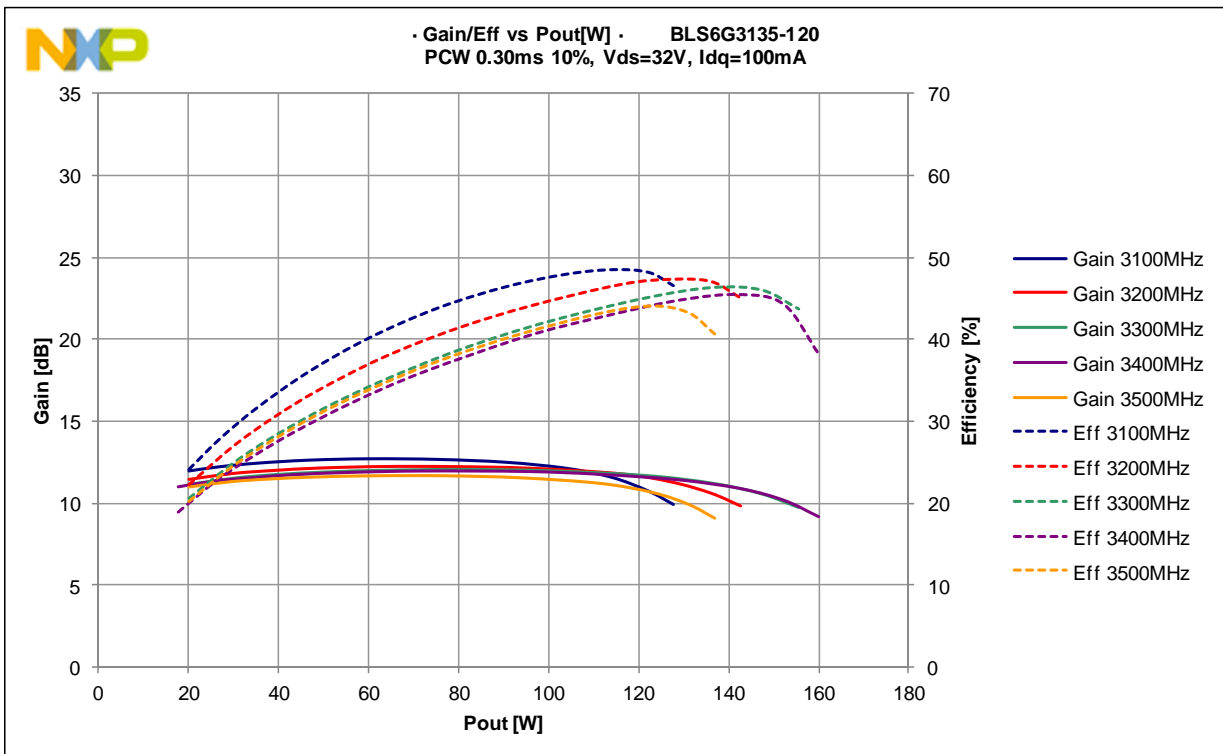
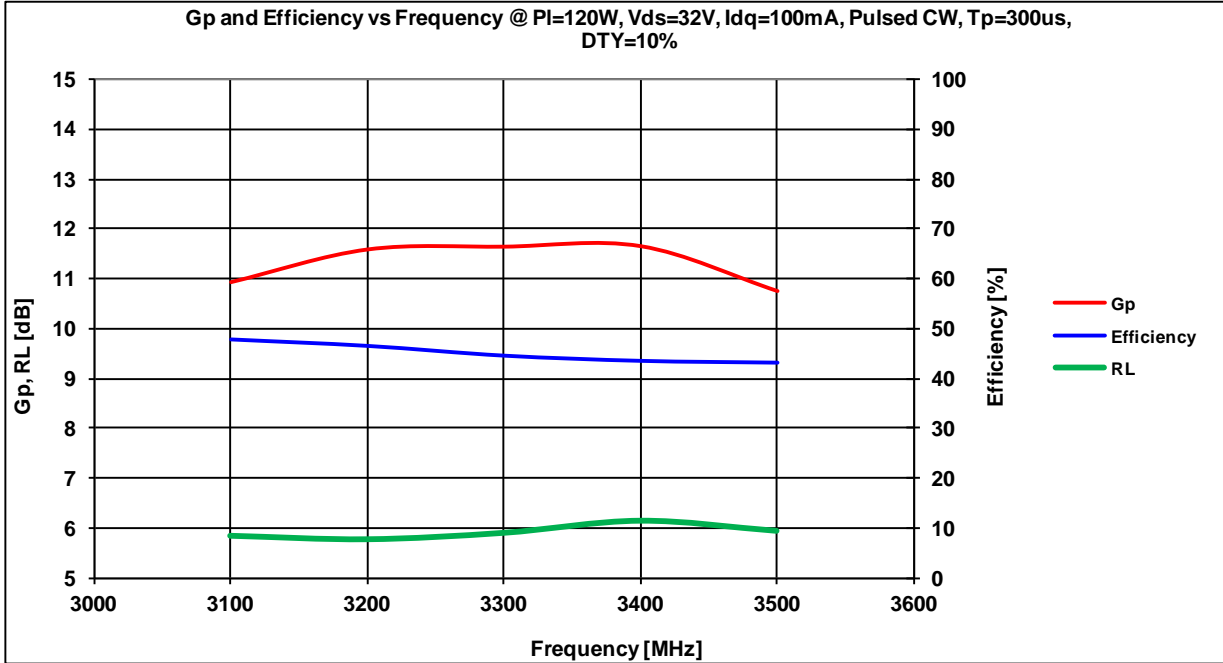
*NOTE: Use an Electrolytic Capacitor of 10000uF parallel to the  $V_{ds}$  as close as possible to the demo board. This delivers the current peaks to the demo board.*

### 1.2 Test circuit

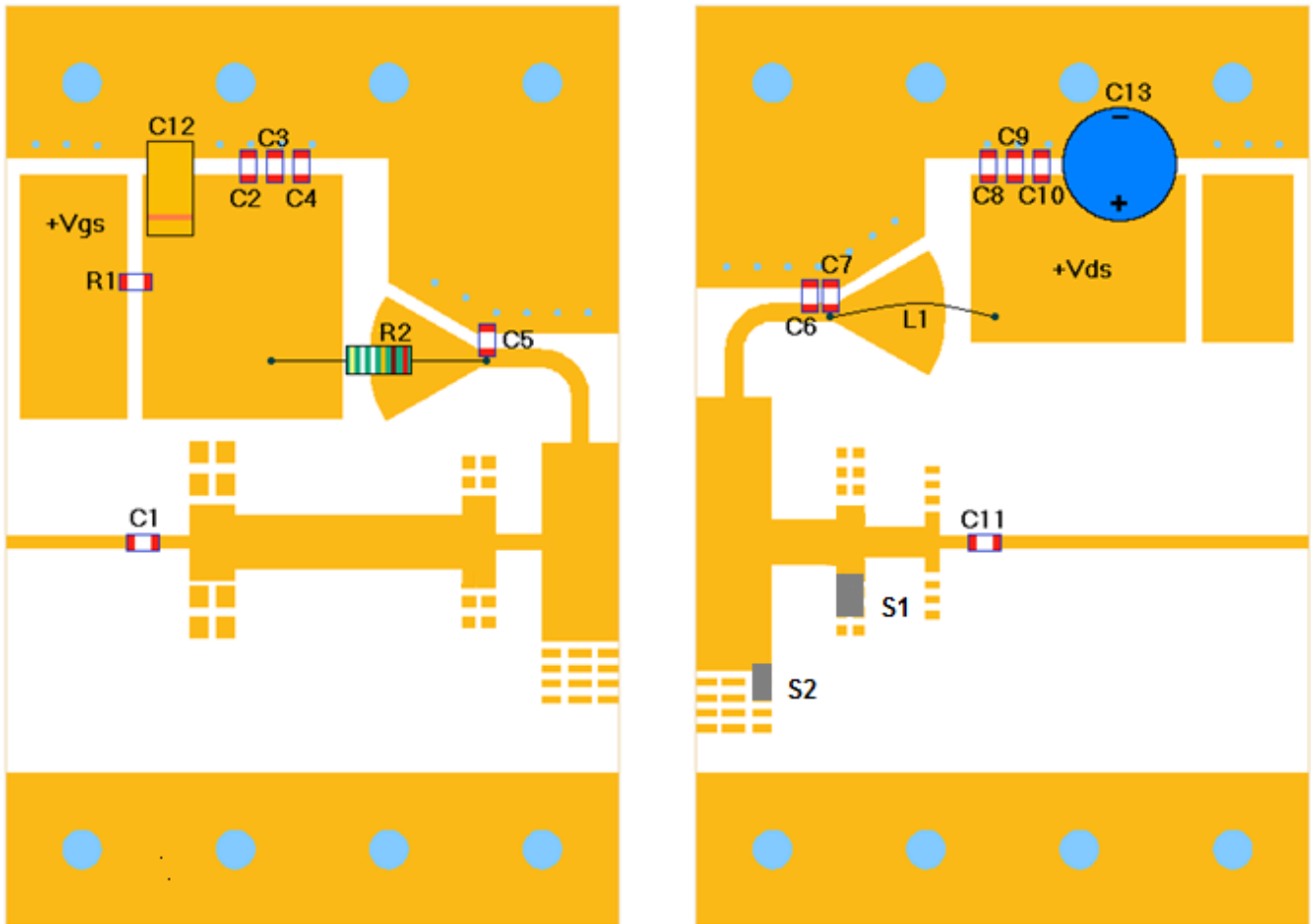
A description of this circuit can be found in **chapter** Error! Reference source not found.. The test circuit has been designed on Duriod 6006, 0.64mm thick,  $\epsilon_r=6.16$ .

## 2. Measurement Results

### 2.1 Test Results Frequency Sweep and Power Sweep:

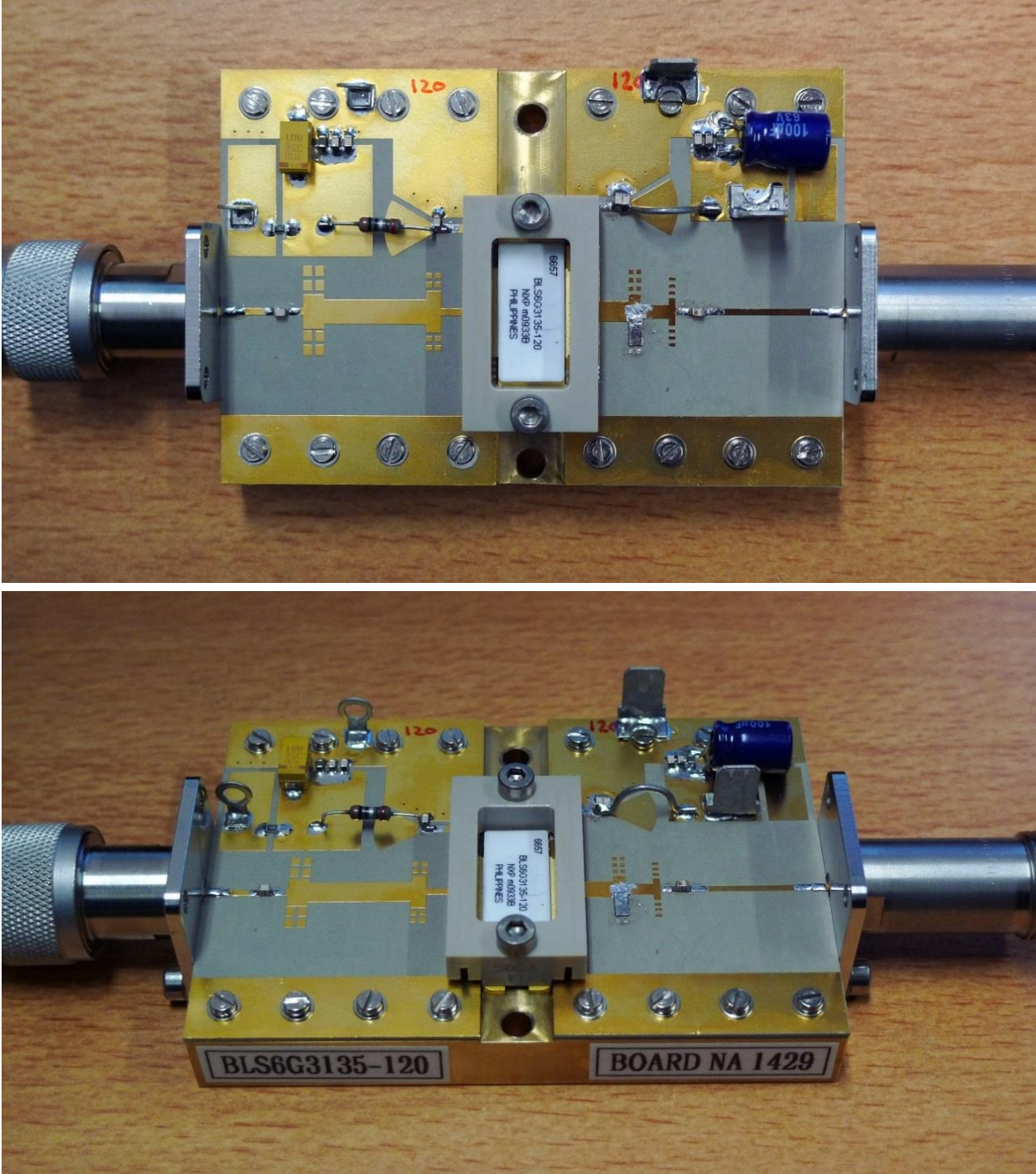


### 3. Test Circuit and List of Components



List of components	
Component	Description
C1,C3,C4,C5,C6,C7,C8,C9,C11	24pF ATC100A
C2,C10	1nF ATC700A
C12	47uF/20V Tantalum
C13	100uF/63V
R1	56 Ohm SMD
R2	49.9 Ohm / 0.6W MetalFilm
S1	Metal Strip
L1	Copper wire 1mm diameter, length=16mm
Pcb-material=Duriod 6006,E r=6.16, H=0.64mm, 2x Cu	

### 4. Photos Demo Board



### 5. Attachments

Please see the attachment for the support files.

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7. Contents

- 1. Introduction ..... 3
- 1.1 General information..... 3
- 1.2 Test circuit..... 3
- 2. Measurement Results ..... 4
- 2.1 Test Results Frequency Sweep and Power  
Sweep: ..... 4
- 3. Test Circuit and List of Components..... 5
- 4. Photos Demo Board..... 6
- 5. Attachments..... 6
- 6. Legal information ..... 7
- 6.1 Definitions ..... 7
- 6.2 Disclaimers..... 7
- 6.3 Trademarks..... 7
- 7. Contents..... 8

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